

WHAT IS CLAIMED IS:

1. A cooling system for a computer case comprising:  
a thermoelectric module;  
a first fan unit for discharging heat from a hot side of the thermoelectric module; and  
a second fan unit for circulating cool air from a cold side of the thermoelectric module.
2. A cooling system for a computer case in accordance with Claim 1 further comprising an insulator plate positioned around the thermoelectric module for preventing heat from the hot side of the thermoelectric module from going to the cold side of the thermoelectric module.
3. A cooling system for a computer case in accordance with Claim 1 wherein the first fan unit comprises:  
a first heatsink coupled to the hot side of the thermoelectric module for dissipating heat from the hot side of the thermoelectric module; and  
a first fan coupled to the first heat sink for dissipating the heat from the first heat sink and the hot side of the thermoelectric module.

4. A cooling system for a computer case in accordance with Claim 1 wherein the second fan unit comprises:

a second heatsink coupled to the cold side of the thermoelectric module; and

a second fan coupled to the second heat sink for dissipating the cool air from the second heat sink and the cold side of the thermoelectric module.

5. A cooling system for a computer case in accordance with Claim 4 further comprising molding coupled to the second heatsink for circulating the cool air around the heat sink to further cool the air prior to the second fan dissipating the cool air from the second heat sink and the cold side of the thermoelectric module.

6. A cooling system for a computer case in accordance with Claim 1 further comprising a freon cooler coupled to the second fan unit for circulating colder air inside the computer case.

7. A cooling system for a computer case in accordance with Claim 6 wherein the freon cooler comprises:

a freon storage device;

a spray mechanism coupled to the freon storage device for dispensing the freon stored inside the freon storage device;

a third heat sink on which the spray mechanism will dispense the freon onto; and

a third fan coupled to the third heat sink for circulating the colder air from the freon cooler inside the computer case.

8. A cooling system for a computer case in accordance with Claim 7 further comprising ducting coupled to the freon cooler for directing the colder air from the freon cooler to a processor unit of the computer case.

9. A cooling system for a computer case comprising:  
a thermoelectric module;  
a first fan unit for discharging heat from a hot side of the thermoelectric module;  
a second fan unit for circulating cool air from a cold side of the thermoelectric module;  
an insulator plate positioned around the thermoelectric module for preventing heat from the hot side of the thermoelectric module from going to the cold side of the thermoelectric module;  
and  
a freon cooler coupled to the second fan unit for generating and circulating colder air inside the computer case.

10. A cooling system for a computer case in accordance with Claim 9 wherein the first fan unit comprises:  
a first heatsink coupled to the hot side of the thermoelectric module for dissipating heat from the hot side of the thermoelectric module; and  
a first fan coupled to the first heat sink for dissipating the heat from the first heat sink and the hot side of the thermoelectric module.

11. A cooling system for a computer case in accordance with Claim 9 wherein the second fan unit comprises:

a second heatsink coupled to the cold side of the thermoelectric module; and

a second fan coupled to the second heat sink for dissipating the cool air from the second heat sink and the cold side of the thermoelectric module.

12. A cooling system for a computer case in accordance with Claim 11 further comprising molding coupled to the second heatsink for circulating the cool air around the heat sink to further cool the air prior to the second fan dissipating the cool air from the second heat sink and the cold side of the thermoelectric module.

13. A cooling system for a computer case in accordance with Claim 9 wherein the freon cooler comprises:

a freon storage device;

a spray mechanism coupled to the freon storage device for dispensing the freon stored inside the freon storage device;

a third heat sink on which the spray mechanism will dispense the freon onto; and

a third fan coupled to the third heat sink for circulating the colder air from the freon cooler inside the computer case.

14. A cooling system for a computer case in accordance with Claim 13 further comprising ducting coupled to the freon cooler for directing the colder air from the freon cooler to a processor unit of the computer case.

15. A cooling system for a computer case comprising:
- a thermoelectric module having a hot side and a cold side;
  - a first fan unit for discharging heat from the hot side of the thermoelectric module wherein the first fan unit comprises:
    - a first heatsink coupled to the hot side of the thermoelectric module for dissipating heat from the hot side of the thermoelectric module; and
    - a first fan coupled to the first heat sink for dissipating the heat from the first heat sink and the hot side of the thermoelectric module;
  - a second fan unit for circulating cool air from the cold side of the thermoelectric module wherein the second fan unit comprises:
    - a second heatsink coupled to the cold side of the thermoelectric module; and
    - a second fan coupled to the second heat sink for dissipating the cool air from the second heat sink and the cold side of the thermoelectric module;
  - an insulator plate positioned around the thermoelectric module for preventing heat from the hot side of the thermoelectric module from going to the cold side of the thermoelectric module;
  - and

a freon cooler coupled to the second fan unit for generating and circulating colder air inside the computer case wherein the freon cooler comprises:

a freon storage device;

a spray mechanism coupled to the freon storage device for dispensing the freon stored inside the freon storage device;

a third heat sink on which the spray mechanism will dispense the freon onto; and

a third fan coupled to the third heat sink for circulating the colder air from the freon cooler inside the computer case.



16. A cooling system for a computer case in accordance with Claim 15 further comprising molding coupled to the second heatsink for circulating the cool air around the heat sink to further cool the air prior to the second fan dissipating the cool air from the second heat sink and the cold side of the thermoelectric module.

17. A cooling system for a computer case in accordance with Claim 15 further comprising ducting coupled to the freon cooler for directing the colder air from the freon cooler to a processor unit of the computer case.